

MBRA120ET3

Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Optimized for Low Leakage Current

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL94, V_O at 1/8"
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- Available in 12 mm Tape, 5000 Units per 13 inch Reel
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)
Human Body Model, 3B (>8000 V)
- Marking: B1E2

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	V
Average Rectified Forward Current (At Rated V _R , T _C = 125°C)	I _O	1.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	40	A
Storage Temperature	T _{stg}	-55 to +150	°C
Operating Junction Temperature	T _J	-55 to +150	°C
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs



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SCHOTTKY BARRIER RECTIFIER 1 AMPERE 20 VOLTS



**SMA
CASE 403D
PLASTIC**

MARKING DIAGRAM



B1E2 = Device Code

ORDERING INFORMATION

Device	Package	Shipping†
MBRA120ET3	SMA	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



MBRA120ET3

THERMAL CHARACTERISTICS

Characteristic	Symbol	5 mm x 5 mm (Note 2)	1 Inch x 1/2 inch (Note 3)	Unit
Thermal Resistance – Junction-to-Lead	$R_{\theta JL}$	34	20	$^{\circ}\text{C}/\text{W}$
Thermal Resistance – Junction-to-Ambient	$R_{\theta JA}$	138	77	

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 1), See Figure 2 ($I_F = 0.1 \text{ A}$) ($I_F = 1.0 \text{ A}$) ($I_F = 2.0 \text{ A}$)	V_F	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	V
		0.455	0.360	
		0.530	0.455	
Maximum Instantaneous Reverse Current, See Figure 4 ($V_R = 20 \text{ V}$) ($V_R = 10 \text{ V}$) ($V_R = 5.0 \text{ V}$)	I_R	$T_J = 25^{\circ}\text{C}$	$T_J = 100^{\circ}\text{C}$	μA
		10	1600	
		1.0	500	
		0.5	300	

1. Pulse Test: Pulse Width $\leq 250 \mu\text{s}$, Duty Cycle $\leq 2\%$.
2. Mounted on a Pad Size of 5 mm x 5 mm, PC Board FR4 (2 pads).
3. Mounted on a Pad Size of 1 inch x 1/2 inch, PC Board FR4 (2 pads).

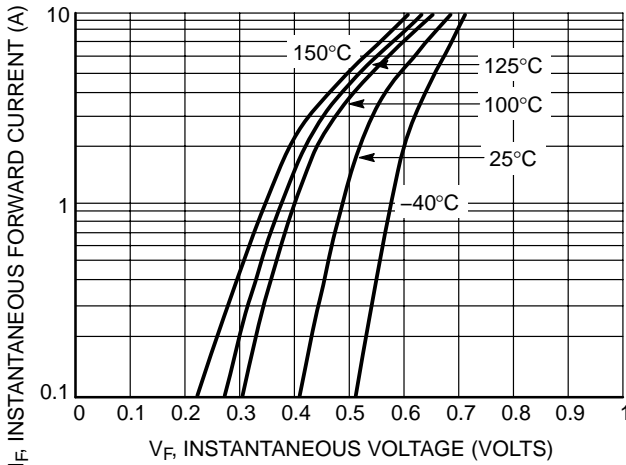


Figure 1. Typical Forward Voltage

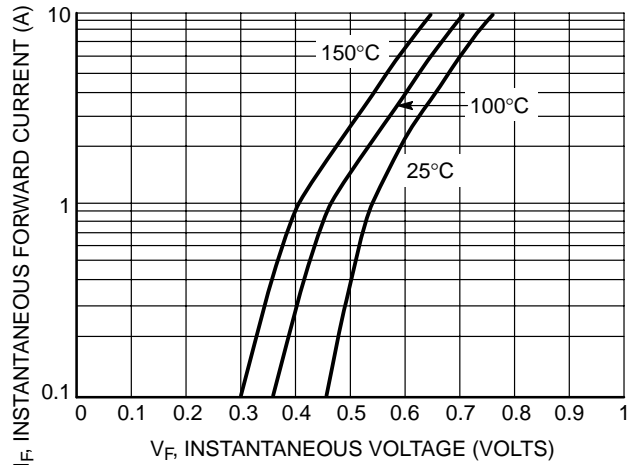


Figure 2. Maximum Forward Voltage

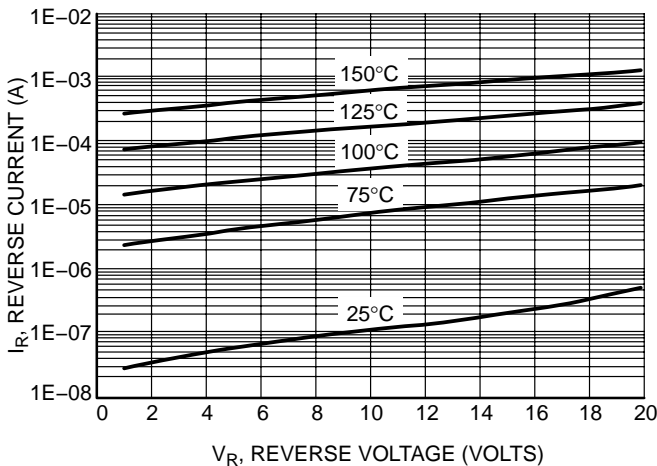


Figure 3. Typical Reverse Current

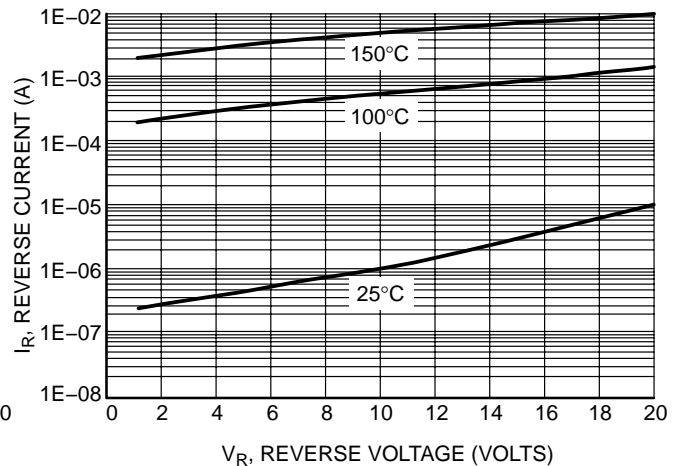


Figure 4. Maximum Reverse Current

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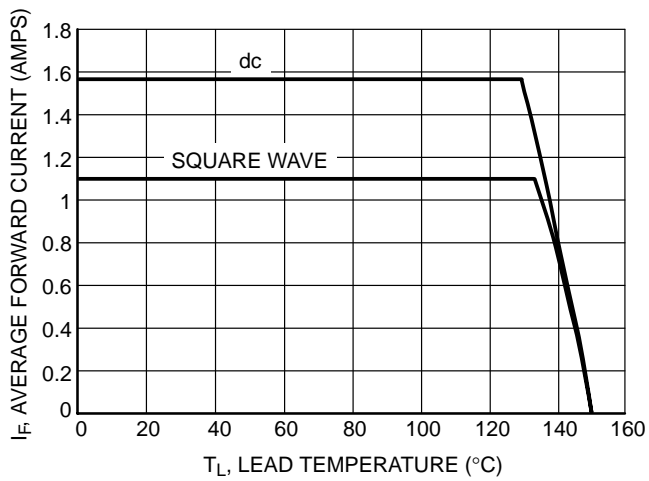


Figure 5. Current Derating

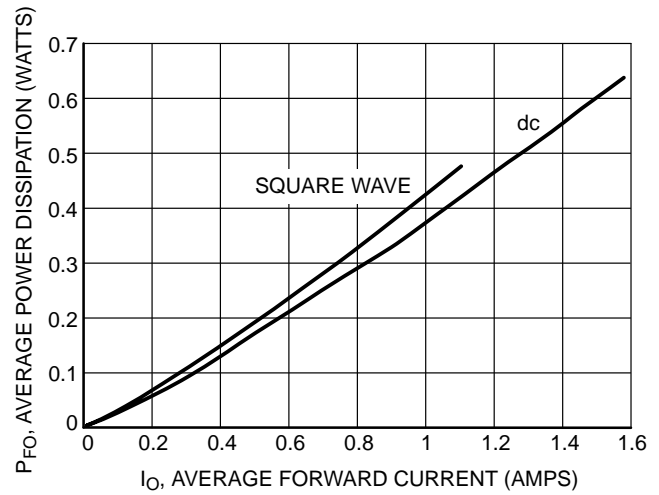


Figure 6. Forward Power Dissipation

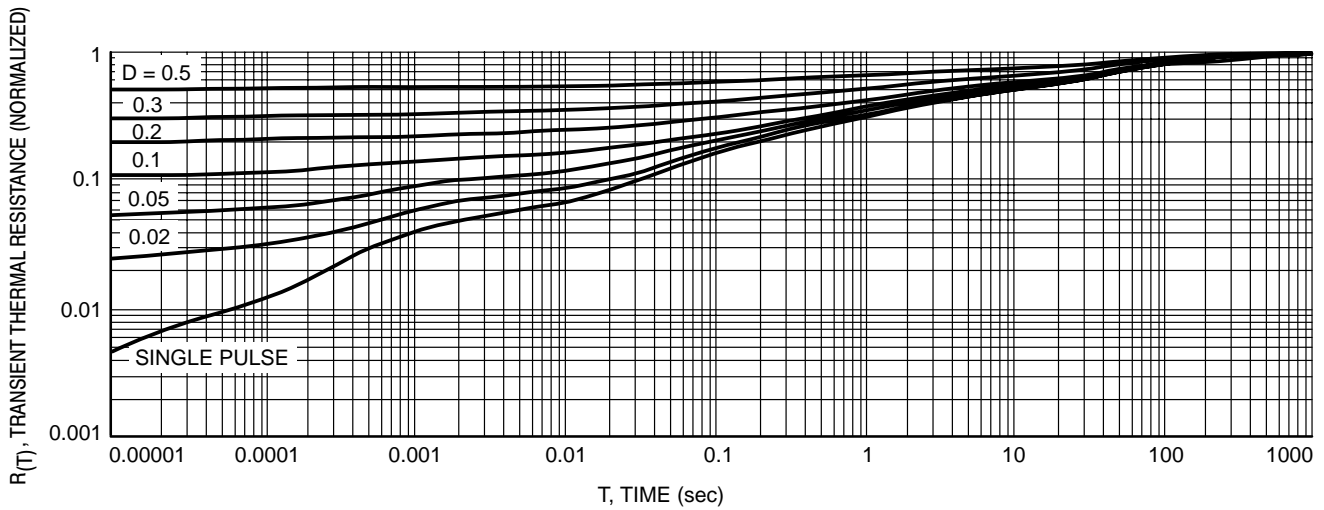


Figure 7. Thermal Resistance

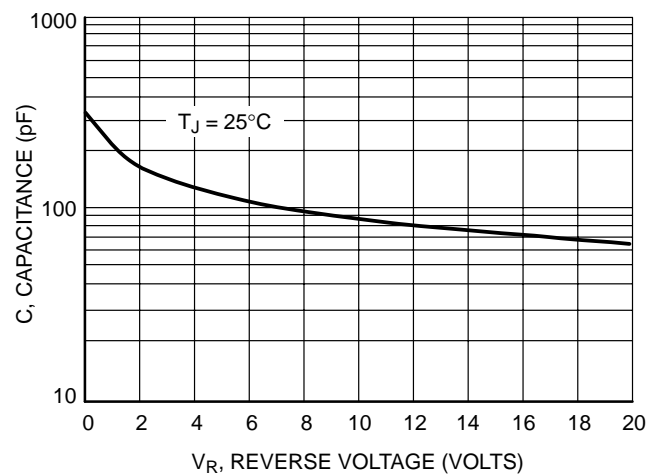
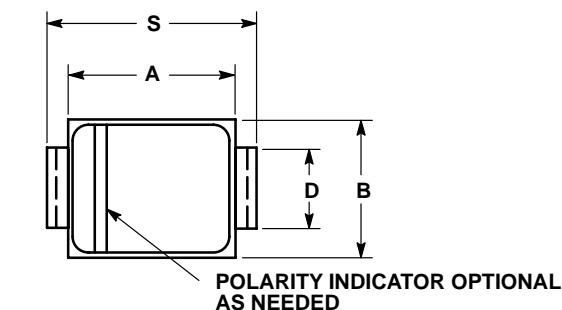


Figure 8. Typical Junction Capacitance

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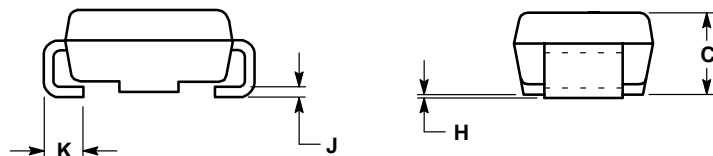
PACKAGE DIMENSIONS

SMA
CASE 403D-02
ISSUE A

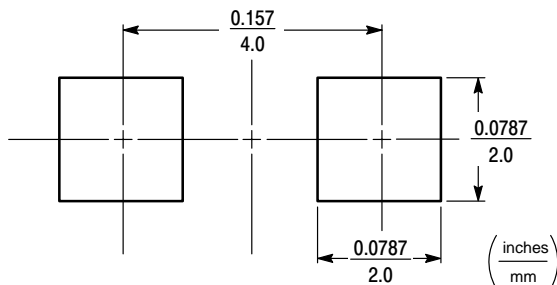


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.160	0.180	4.06	4.57
B	0.090	0.115	2.29	2.92
C	0.075	0.095	1.91	2.41
D	0.050	0.064	1.27	1.63
H	0.002	0.006	0.05	0.15
J	0.006	0.016	0.15	0.41
K	0.030	0.060	0.76	1.52
S	0.190	0.220	4.83	5.59




SOLDERING FOOTPRINT*



SMA FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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